

Preliminary Amendment

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Title: PROCESS FOR PRODUCING AND APPARATUS FOR IMPROVING THE BONDING BETWEEN A PLASTIC AND A METAL

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

A semiconductor having a leadframe is disclosed. In one embodiment, a leadframe is disclosed to be fitted with a semiconductor chip (2) and is to be encapsulated with a plastic compound (4) has a metallic single-piece base body (3), to which an interlayer (5) is applied. The interlayer (5) has a surface (6) ~~comprising~~including a matrix of islands (14) of remaining material of substantially uniform height, with voids (10) extending between said islands.

[Figure 1]